Dear author(s),

**Paper ID**    :        **IEMT-EMAP2016-XXX.**

**Paper Title   :**

On behalf of the Technical Program Committee of the 37th International Electronics Manufacturing Technology Conference and 18th Electronics Materials & Packaging Conference (IEMT-EMAP2016), we are pleased to inform you that your above-mentioned abstract has been accepted for oral presentation at the conference.

Please note that you, or at least one of your co-authors should register for the conference in order to be able to present the paper.  The pre-registration period is open from today. Please submit the PDF file of your full-length paper\* by **June 15th, 2016** for publication in the conference proceedings. The required format for the preparation of your camera-ready paper will be available for downloading from the IEMT-EMAP2016 website at <http://ewh.ieee.org/r10/malaysia/cpmt/Home/iemt/2016/iemt2016.html>. An Author Kit with other relevant information will also be available on-line on the same website.  We will have your session assignment and session co-chairs available and ready for downloading soon.

Please confirm to our secretariat that you will be able to prepare this paper and that either you or the co-author will deliver the oral presentation at IEMT-EMAP2016 on September 20th – 22nd, 2016.  Please also consider attending one of the short courses offered at the conference.

Should you require any assistance, please feel free to contact us via [iemt-emap2016@crest.my](mailto:iemt-emap2016@crest.my).  In all correspondence, please quote your paper number for our reference. We look forward to meeting you at IEMT-EMAP2016 in Penang, Malaysia.

Sincerely,

*Mohd Nasir Tamin (UTM)*

*Chew Chee Hiong (ON Semi)*

*Sim Jit Shen (Infineon)*

Technical Program Committee, IEMT2016

*\* The author may also send the word format of their papers but IEMT2016 will only distribute the pdf version of their papers in a flash drive to all conference participants.  No hardcopy printing of the papers will be provided.*

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37th International Electronics Manufacturing Technology Conference and 18th Electronics Materials & Packaging Conference (IEMT-EMAP2016)

Secretariat:

**Hafiza Hamid**

IEMT-EMAP2016 Conference

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